DOCUMENT: M20099 **REV LETTER: G** PAGE NO: 1 OF 1 REV DATE: 2019-11-25 PART NUMBER:

Polymer PTC Devices

Wayon Electronics Co., Ltd.

No.1001, Shiwan 7th Road, Pudong, Shanghai 201202, P.R. China

Tel: 86-21-50968309 Fax: 86-21-50968310

E-mail: market@way-on.com Http://www.way-on.com



LM130F

Surface mount fuses

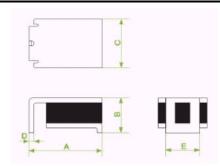
Features

- Surface mount devices
- Withstanding high interrupt voltage
- Lead-free and compliant with the European Union RoHS Directive 2011/65/EU

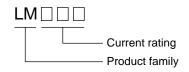


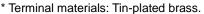
Product Dimensions (mm)

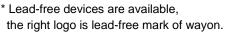
Part number	Α	В	С	D	E
	Тур.	Тур.	Тур.	Тур.	Тур.
LM130F	9.10 ± 0.30	3.15 ± 0.25	7.00 ± 0.40	0.30 ± 0.05	3.80 ± 0.30



Marking system









Electrical Characteristics

Part	I _H	Ι _Τ	Max. Time-to-trip		V_{max}	I _{max}	Pd _{typ}	R_{min}	R_{max}	R _{1max}
number	(A)	(A)	Current(A)	Time(s)	(V)	(A)	(W)	(Ω)	(Ω)	(Ω)
LM130F	0.13	0.26	1.00	2.5	250	3.0	3.0	6.5	12.0	20.0

 I_H =Hold current: maximum current at which the device will not trip at 25 $^{\circ}$ C still air. I_T =Trip current: minimum current at which the device will always trip at 25 $^{\circ}$ C still air.

Max. Time-to-trip =Maximum time to trip(s) at assigned current.

V_{max}=Maximum voltage device can withstand without damage at rated current.

I_{max}=Maximum fault current device can withstand without damage at rated voltage.

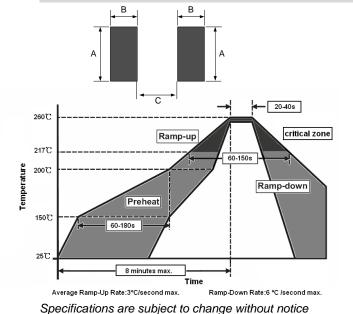
Pd_{typ}=Typical power dissipation: typical amount of power dissipated by the device when in state air environment.

R_{min}=Minimum device resistance at 25°C prior to tripping.
R_{max}=Maximum device resistance at 25°C prior to tripping.
R_{1max}=Maximum device resistance at 25°C one hour post trip.

Thermal Derating Chart-IH(A)

LM130F	Maximum ambient operating temperatures(℃)								
	-40	-20	0	25	40	50	60	70	85
Hold Current (A)	0.208	0.182	0.156	0.130	0.104	0.091	0.078	0.065	0.045
Trip Current (A)	0.416	0.364	0.312	0.260	0.208	0.182	0.156	0.130	0.090

Solder Reflow Recommendations



Solder Pad Layouts

Dout would be	Α	В	С	
Part number -	(mm)	(mm)	(mm)	
LM130F	4.6	1.8	6.1	

- Recommended reflow methods: IR, Vapor phase oven, hot air oven.
- * Devices can be cleaned using standard industry methods and solvents.

Notes:

If reflow temperatures exceed the recommended profile, devices may not meet the performance requiremen

Package Information Bulk: 1000pcs per bag.

Tape & Reel: 1500pcs per reel.